

XP05555 (XP5555)

Silicon NPN epitaxial planer transistor

For high speed switching

■ Features

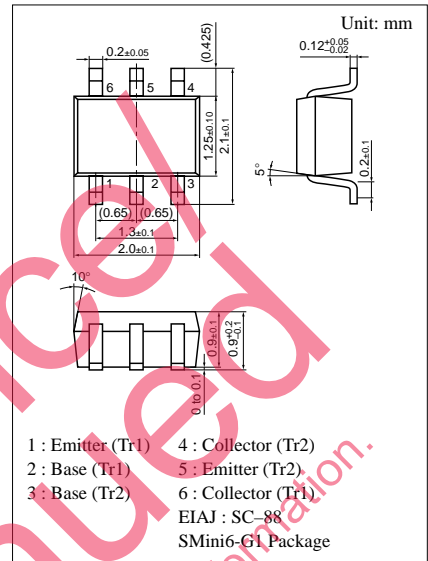
- Two elements incorporated into one package.
- Reduction of the mounting area and assembly cost by one half.

■ Basic Part Number of Element

- 2SC4782 × 2 elements

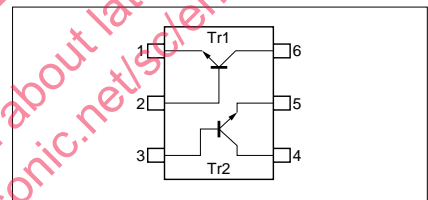
■ Absolute Maximum Ratings (Ta=25°C)

	Parameter	Symbol	Rated	Unit
Rating of element	Collector to base voltage	V_{CBO}	25	V
	Collector to emitter voltage	V_{CES}	20	V
	Emitter to base voltage	V_{EBO}	5	V
	Collector current	I_C	200	mA
	Peak collector current	I_{CP}	300	mA
Overall	Total power dissipation	P_T	150	mW
	Junction temperature	T_j	150	°C
	Storage temperature	T_{stg}	-55 to +150	°C



Marking Symbol: EO

Internal Connection

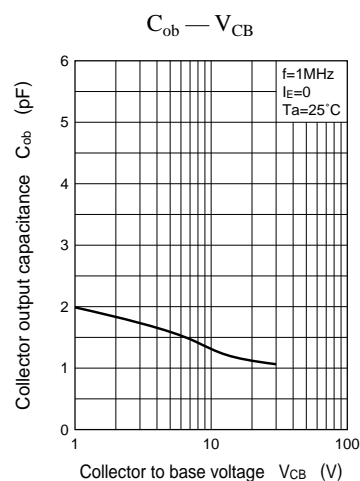
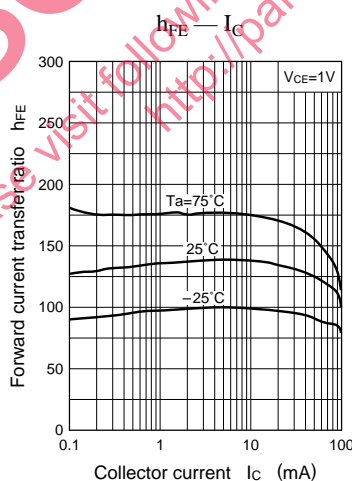
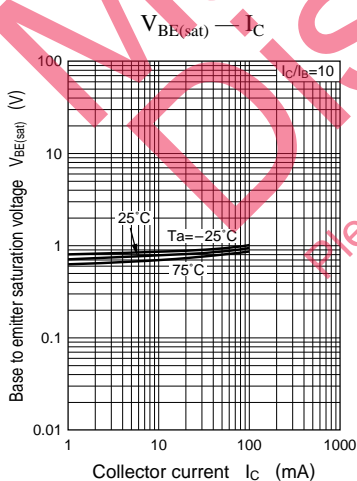
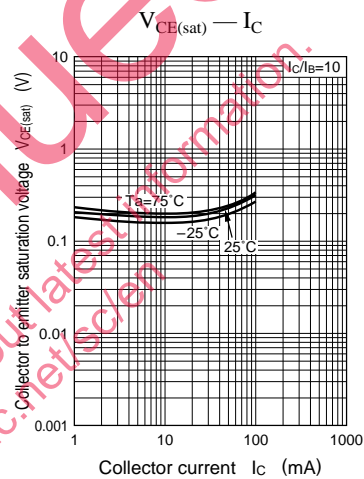
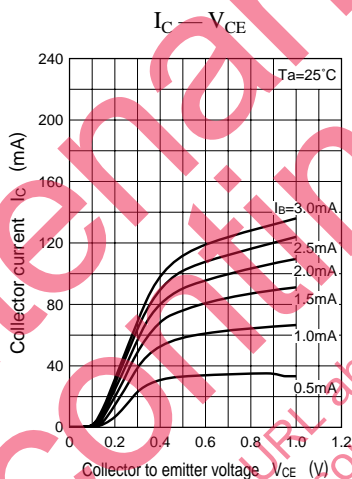
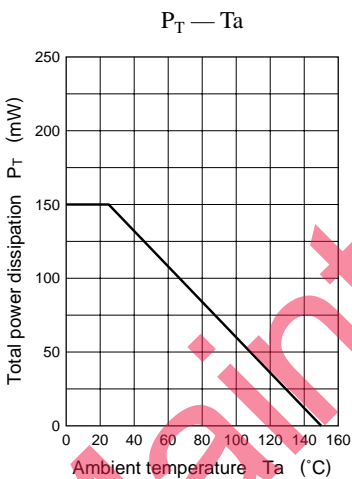
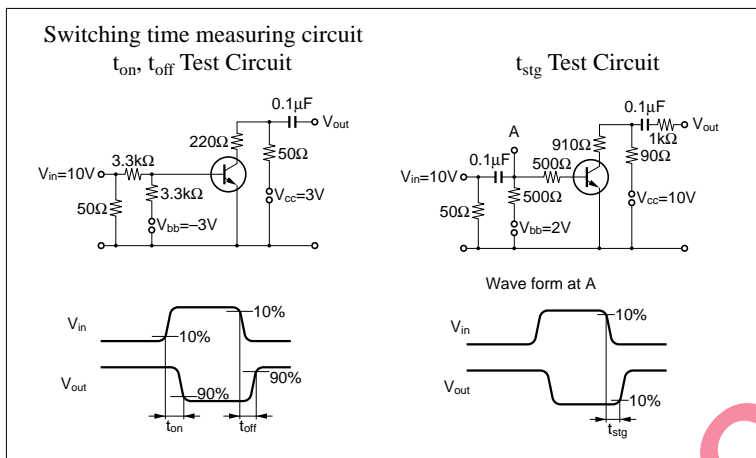


■ Electrical Characteristics (Ta=25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	I_{CBO}	$V_{CB} = 10V, I_E = 0$			0.1	μA
Emitter cutoff current	I_{EBO}	$V_{EB} = 4V, I_C = 0$			0.1	μA
Forward current transfer ratio	h_{FE}	$V_{CE} = 1V, I_C = 10mA$	40		200	
Collector to emitter saturation voltage	$V_{CE(sat)}$	$I_C = 10mA, I_B = 1mA$		0.17	0.25	V
Base to emitter saturation voltage	$V_{BE(sat)}$	$I_C = 10mA, I_B = 1mA$		0.76	1.0	V
Transition frequency	f_T	$V_{CB} = 10V, I_E = -10mA, f = 200MHz$		200	500	MHz
Collector output capacitance	C_{ob}	$V_{CB} = 10V, I_E = 0, f = 1MHz$		2	4	pF
Turn-on time	t_{on}	*1		17		ns
Turn-off time	t_{off}			15		ns
Storage time	t_{stg}			7		ns

*1 Switching time measuring circuit

Note) The Part number in the Parenthesis shows conventional part number.



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